

3.5x2.8 mm SMD CHIP LED LAMP

PRELIMINARY SPEC



ATTENTION
OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE **DEVICES**

Part Number: AA3529QB24ZS

BLUE

Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- WHITE SMD PACKAGE, SILICONE RESIN.
- LOW THERMAL RESISTANCE.
- PACKAGE: 1500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 2a.
- RoHS COMPLIANT.

Description

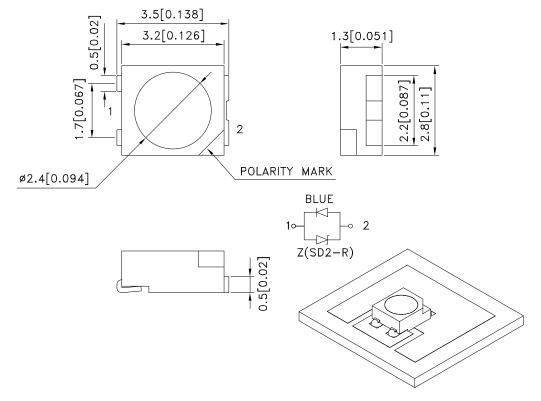
The Blue source color devices are made with InGaAIN Vertical Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Specifications are subject to change without notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAH9589 APPROVED: WYNEC

REV NO: V.3 CHECKED: Allen Liu **DATE: JUL/10/2008** DRAWN: R.CHEN

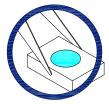
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

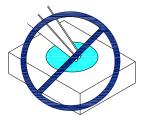
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

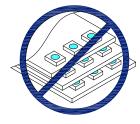


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

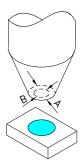




Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 150mA		Фv (mlm) [2] @ 150mA		Viewing Angle [1]
			Min.	Тур.	Min.	Тур.	2 θ 1/2
AA3529QB24ZS	BLUE (InGaAIN)	WATER CLEAR	650	1000	4000	6000	120°

Notes:

 $1.0\,$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	Pt	585	mW	
Junction Temperature [1]	TJ	110	°C	
Operating Temperature	Тор	-40 To +85	°C	
Storage Temperature	Tstg	-40 To +85	°C	
DC Forward Current [1]	lF	150	mA	
Peak Forward Current [2]	Iғм	270	mA	
Thermal Resistance [1] (Junction/ambient)	Rth j-a	180	°C/W	
Thermal Resistance [1] (Junction/solder point)	Rth j-S	60	°C/W	
Electrostatic Discharge Threshold (HBM)	8000	V		

Notes

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Wavelength at peak emission IF=150mA [Typ.]	λ peak	450	nm	
Dominant Wavelength IF=150mA [Typ.]	λ dom [1]	457	nm	
Spectral Line Half-width Ir=150mA [Typ.]	Δλ	20	nm	
Forward Voltage IF=150mA [Min.]		3.1		
Forward Voltage IF=150mA [Typ.]	VF [2]	3.5	V	
Forward Voltage IF=150mA [Max.]		3.9		
Temperature coefficient of λ peak IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC λ peak	0.13	nm/° C	
Temperature coefficient of λ dom IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC λ dom	0.1	nm/° C	
Temperature coefficient of VF IF=150mA, -10 ° C≤ T≤100 ° C [Typ.]	TCv	-3.1	mV/° C	

Notes:

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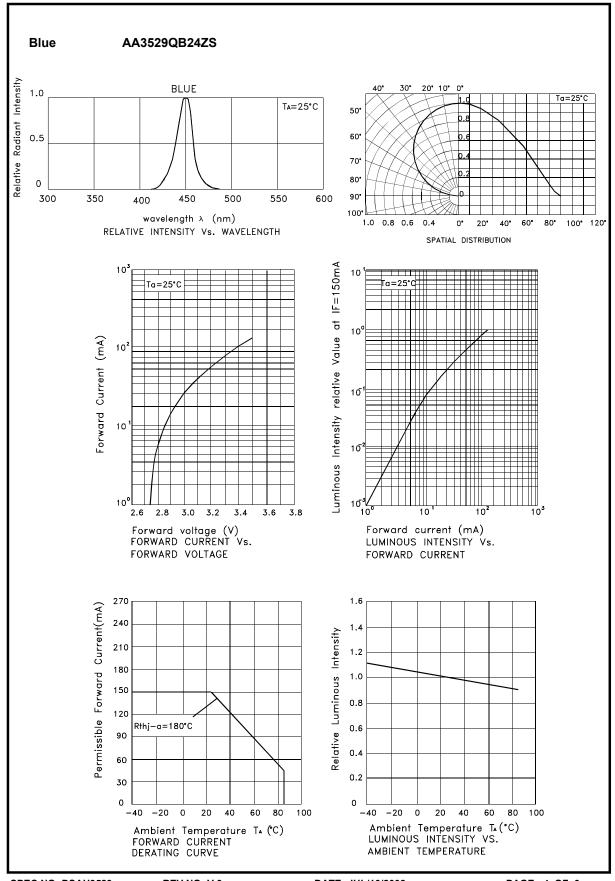
^{2.}Luminous Intensity/ Luminous Flux: +/-15%

^{1.}Results from mounting on PC board FR4(pad size ≥ 70mm²), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

^{2.1/10} Duty Cycle, 0.1ms Pulse Width.

^{1.}Wavelength: +/-1nm.

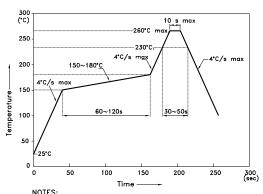
^{2.} Forward Voltage: +/-0.1V.



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AA3529QB24ZS

Reflow Soldering Profile For Lead-free SMT Process.



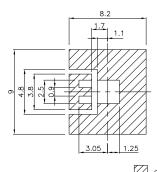
NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

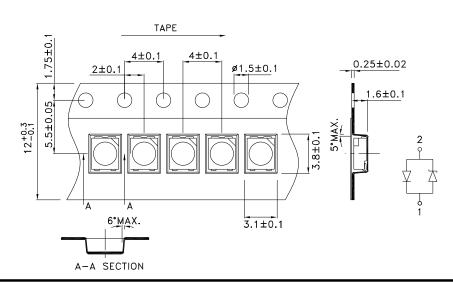
Recommended Soldering Pattern

(Units: mm; Tolerance: ±0.1)

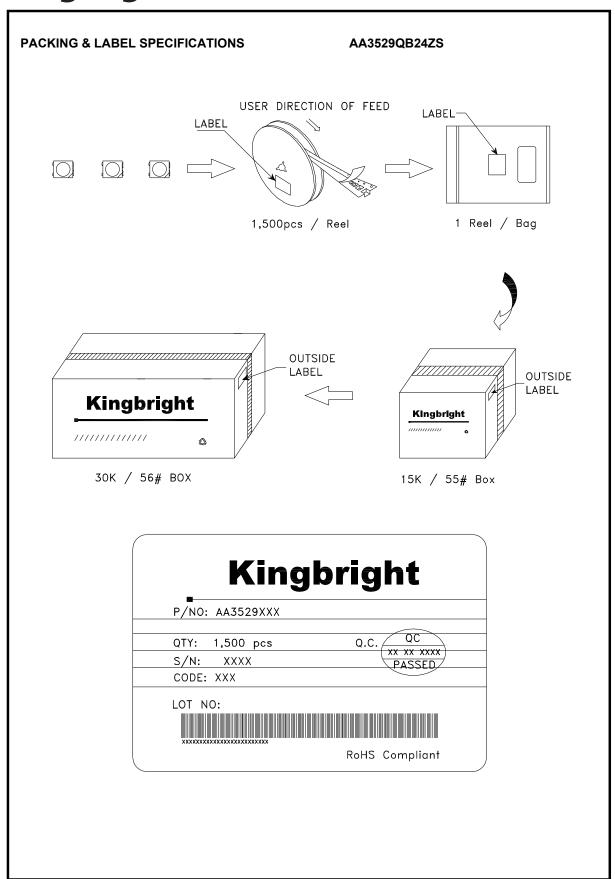


Solder Mask

Tape Specifications (Units: mm)



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